

sub C1

1. (Amended)

A semiconductor package for enhancing heat

dissipation, comprising:

a die having an active surface;

a leadframe, including:

a die pad having a first surface and a second surface, said die being attached to said first surface of the die pad; and

a plurality of leads electrically connected to the active surface of said die, said leads having a surface;

an encapsulant sealing said die and at least a portion of the surface of the leads in said leadframe; and

a heat sink attached to the second surface of said die pad and at least a portion of the surface of leads in said plurality of leads with a thermally conductive and electrically insulating adhesive glue, said heat sink being exposed to ambient atmosphere and not encapsulated in said encapsulant.

R E M A R K S

Careful consideration has been given to the Official Action of November 8, 2002 and reconsideration of the application is respectfully requested.

Claim 1 has been amended to correct a typographical error.